

Lasers in electronics production

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asers in electronics production



Posa - to put Lux - Light

From Radium to Laser



Providing high-tech micromachining solutions

Since 1943 | Headquarters in Biel/Bienne, Switzerland.

• **Expertise in high-tech micromachining** solutions tailored to meet the evolving needs of the industry

• **Proven reliability:** Trusted for durable, high-precision performance in mass production environments

• **Market leadership:** Committed to continuous innovation and excellence in micromachining technology

• **Innovation at the core** of our work, driven by our people to create machines that exceed expectations





What is Electronic Test Equipment? – Understanding Probe Cards



•100s of chips manufactured per wafer

•Low yield rate of high end complex chips. E.g. Apple M3 chips had yield had as low as 55% yield rate during early production.

(www.laptopmag.com)



What is Electronic Test Equipment? – Understanding Probe Cards



Probes

Probe cards are instruments used to electrically inspect semiconductor wafers. They provide an interface between automatic test equipment (ATE) and the wafer, allowing for testing of integrated circuits (ICs) before they are diced and packaged. These probe cards have **metallic probes** that align with the test point pads on the semiconductor wafer and send signals through them. These probes are held in place by a **guide plate**—a highly precise component that guides the probes towards the test point.



The Challenge – Smaller Chips, More Complexity



2nm technology can pack 50 billion transistors on a chip the size of a fingernail

•Hole diameters continue to shrink: down to 20 μm and smaller

•Wall thickness (between holes) \leq 10 μ m

•Position accuracy $\leq \pm 2 \mu m$

•More holes are needed per guide plate up to hundreds of thousands per plate

E.g. 100 k holes drilled @ 3secs per hole will take 83 hours of drill time only. Missing the above-mentioned accuracy will result in scrapped hardware



The Engine Behind Precision

Ultrafast lasers

- Ultrashort pulses laser source (< 300 fs)
- Precession head with 5 optical axis
- High precision positioning X-Y table
- Interchangeable clamping devices
- Robust and multifunctional software
- Focal length measurement (autofocus)
- Powermeter for laser stability check
- Thermal stability control
- High resolution camera for repositioning jobs





5-axis precession head

- Allows complete geometry achievement
- Avoids any damage on hole shapes



Rigid, thermally stable machine



Hole Geometry





Here you can see the types of holes we've machined

Hole Geometry Portfolio

Step holes





Proof of Precision



DOSCIUX SWISS MADE

20% measurement of 75000 holes

Vertical probes













Probe tips with step







We design the Future of Micromachining